

# エンボステープパッケージングにおける電子デバイスの帯電問題

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## Electrification Subject of the Electron Device in Emboss Tape Packaging

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### Abstract

Recent electric devices, such as LEDs and chip resistances are remarkably decreasing their sizes. Such small devices may be attached to packed cover tape, however, when the tape is removed in an assembly process. This problem often remains even if cover tape is treated with antistatic agents or electroconductive materials because these devices are also charged by contact or friction with cover tape. Alternative packaging materials are required to suppress electrostatic force generated with electric devices.

**Key Words:** *Electron Device, Adhesion, Charge, Suppress Electrification*